



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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REVISION(S)

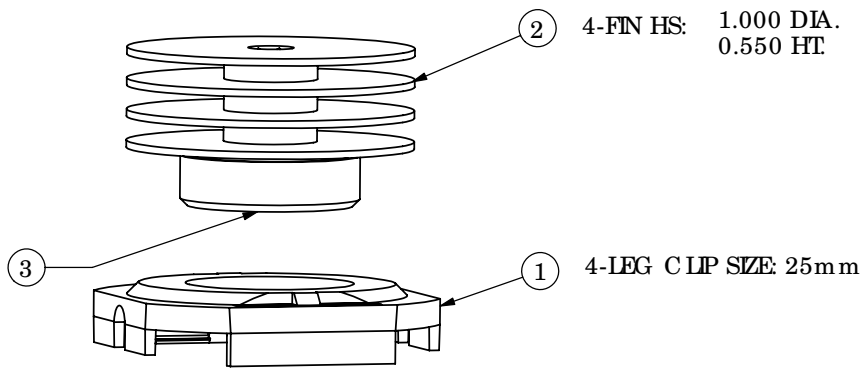
LTR	DESCRIPTION	INIT	APP'D
O	ECN: 0S60-0198-04	E.T 7/29/04	B.P 8/20/04
A	ECR-06-011657	E.T 6/2/06	V.K 6/2/06

D

C

B

A



NOTE:

1. MATERIAL:

HEAT SINK: ALUM. (BLACK ANODIZE)
CLIP: BLACK PEI (UL94-VO)

2. BEFORE THE HEAT SINK APPLICATION, THE USER SHOULD IDENTIFY THE SPECIFICATION OF MAXIMUM LOAD ON THE BGA PACKAGE

HEAT SINK TO REQUIRE SPECIFICATIONS CONVERTED TO FORCE

BARE DIE PACKAGE

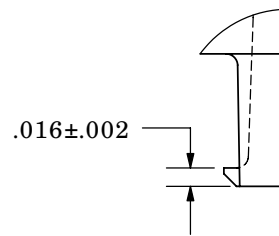
1.5 INCH - LB TO REQUIRE = 8.5 LBS FORCE
2.0 INCH - LB TO REQUIRE = 11.4 LBS FORCE

FULL SIZE LID PACKAGE

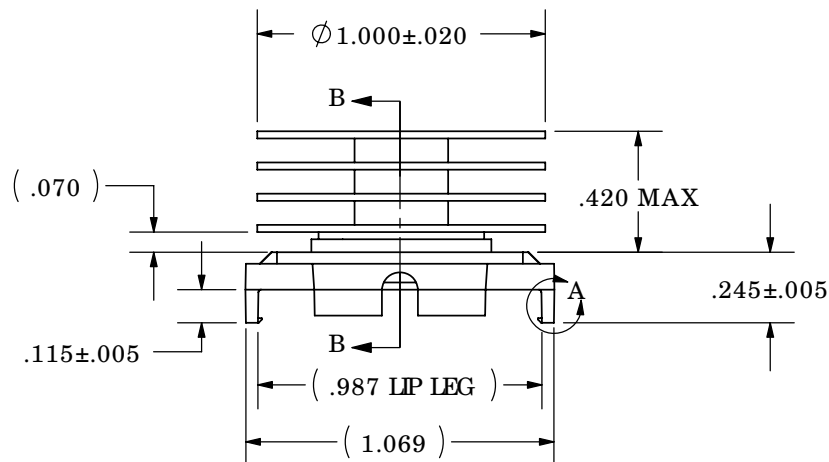
1.5 INCH - LB TO REQUIRE = 8.3 LBS FORCE
2.0 INCH - LB TO REQUIRE = 11.1 LBS FORCE

3. REMOVE CLIP WITH REMOVAL TOOL P/N: 1542616-1.

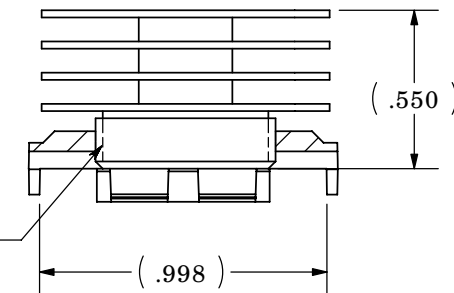
4. RoHS COMPLIANT AND CERTIFIED.



DETAIL A
SCALE = 6X



5/8 - 27 UNS 2A
THREAD



SECTION B-B

CUSTOMER DRAWING

SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE

ITEM	DESCRIPTION	QTY
1	MOUNTING CLIP	1
2	HEAT SINK	1
3	INTERFACE	1

DO NOT SCALE

tyco / Electronics Attleboro Falls Massachusetts 02763

UNLESS OTHERWISE SPECIFIED TO TOLERANCES ARE

DRAWN BY: E.TAO	DATE: 7/28/04	MATERIAL: SEE NOTE
ENGINEER: B. PETROCELLI	DATE: 8/20/04	FINISH: SEE NOTE
FILENAME	PROJECT	SYSTEM

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DIMENSIONS ARE IN: INCHES SCALE: 1.5:1

INRD ANGLE PROJECT TO:

SIZE: A

TITLE: **25mm HS ASSEMBLY (HIS210-U)**

PART NO: **1-1542006-0** SHEET: 1 OF 1

DWG. NO. **C-1-1542006-0** REV: **A**

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